

General Description:

The LWP3009CS uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications. The package form is SOP-8, which accords with the ROHS standard and Halogen Free standard.

Features:

- Fast Switching
- Low Gate Charge and $R_{DS(ON)}$
- Low Reverse transfer capacitances

Applications:

- Battery switching application
- Hard switched and high frequency circuits
- Power Management

100% DVDS Tested

100% Avalanche Tested



Package Marking and Ordering Information:

Marking	Part Number	Package	Packing	Qty.
P3009/LW CS/D.C.	LWP3009CS	SOP-8	Reel	4000 Pcs

Absolute Maximum Ratings:

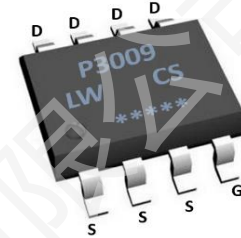
Symbol	Parameter		Value	Units
V_{DSS}	Drain-to-Source Voltage		-30	V
I_D	Continuous Drain Current	$T_A=25^{\circ}\text{C}$	-16	A
	Continuous Drain Current	$T_A=100^{\circ}\text{C}$	-10	A
I_{DM}^{a1}	Pulsed Drain Current		-64	A
E_{AS}^{a2}	Single pulse avalanche energy		175	mJ
V_{GS}	Gate-to-Source Voltage		± 20	V
P_D	Power Dissipation		3.1	W
T_J, T_{STG}	Operating Junction and Storage Temperature Range		150, -55 to 150	$^{\circ}\text{C}$
T_L	Maximum Temperature for Soldering		260	$^{\circ}\text{C}$

Thermal Characteristics:

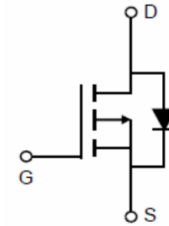
Symbol	Parameter	Value	Units
$R_{\theta JA}^{a3}$	Thermal Resistance, Junction-to-Ambient	40	$^{\circ}\text{C/W}$

V_{DSS}	-30	V
I_D	-16	A
P_D	3.1	W
$R_{DS(ON) \text{ TYPE}}$	6.0	$\text{m}\Omega$

Marking and Pin Assignment



Inner Equivalent Principium Chart



Electrical Characteristic ($T_J = 25\text{ }^{\circ}\text{C}$, unless otherwise specified):

Static Characteristics						
Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
V_{DSS}	Drain to Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-30	--	--	V
I_{DSS}	Drain to Source Leakage Current	$V_{DS}=-30V, V_{GS}=0V$	--	--	-1.0	μA
$I_{GSS(F)}$	Gate to Source Forward Leakage	$V_{GS}=-20V, V_{DS}=0V$	--	--	-100	nA
$I_{GSS(R)}$	Gate to Source Reverse Leakage	$V_{GS}=+20V, V_{DS}=0V$	--	--	100	nA
$V_{GS(TH)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1.1	-1.6	-2.1	V
$R_{DS(ON)1}$	Drain-to-Source On-Resistance	$V_{GS}=-10V, I_D=-15A$	--	6.0	8.0	$m\Omega$
$R_{DS(ON)2}$	Drain-to-Source On-Resistance	$V_{GS}=-4.5V, I_D=-10A$	--	8.5	10.5	$m\Omega$

Dynamic Characteristics						
Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
C_{iss}	Input Capacitance	$V_{GS}=0V$	--	2860	--	pF
C_{oss}	Output Capacitance	$V_{DS}=-15V$	--	416	--	
C_{rss}	Reverse Transfer Capacitance	$f=1.0MHz$	--	385	--	
R_G	Gate resistance	$V_{GS}=0V, V_{DS}=0V, f=1MHz$	--	9.6	--	Ω

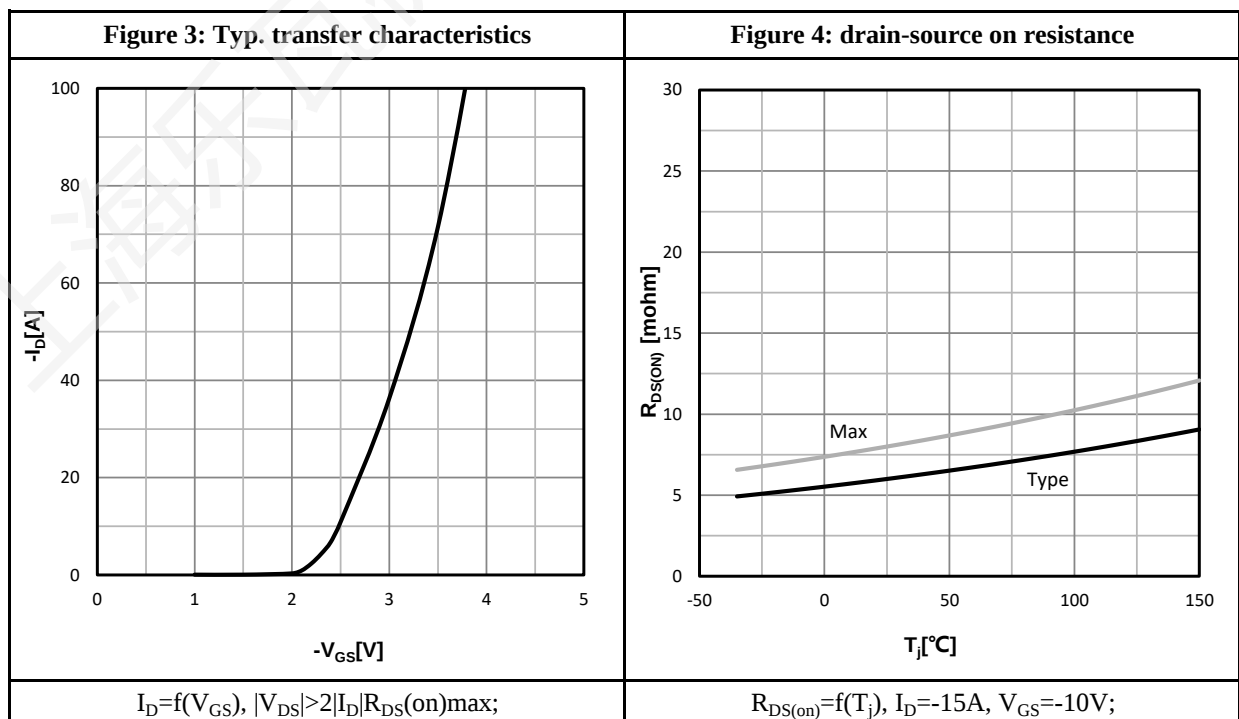
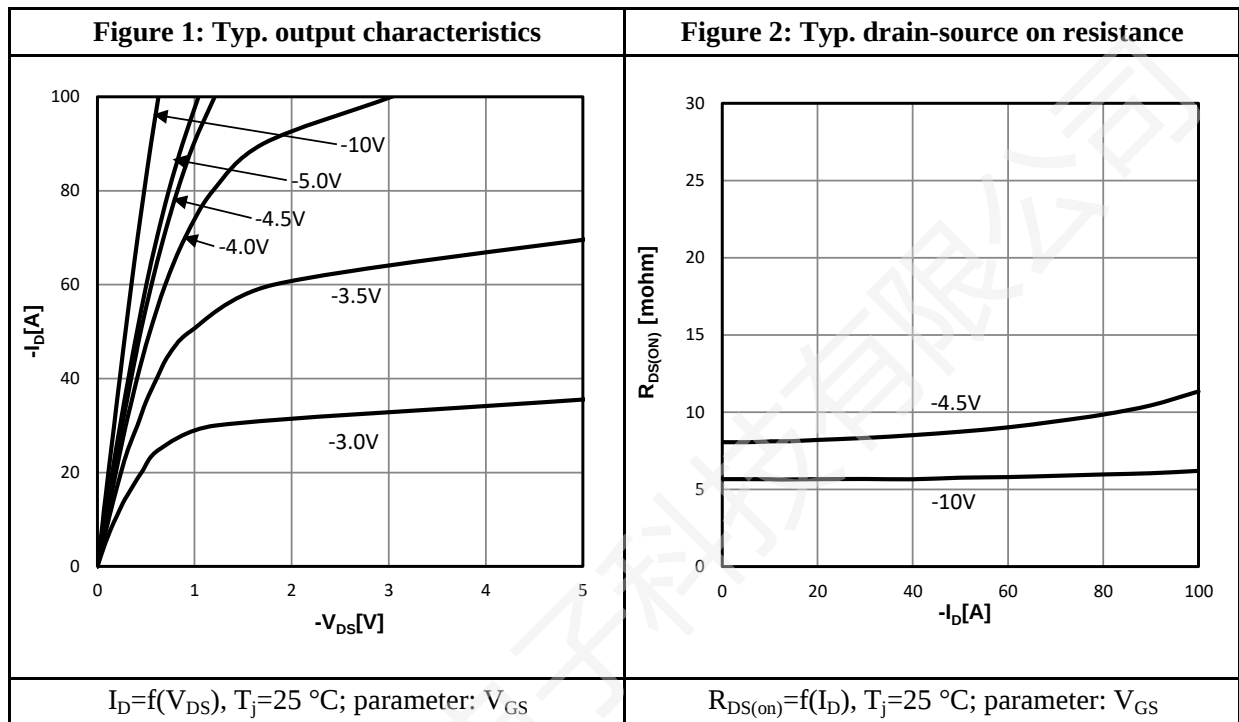
Resistive Switching Characteristics						
Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
$t_{d(ON)}$	Turn-on Delay Time	$I_D=-15A$	--	12.7	--	ns
t_r	Rise Time	$V_{DS}=-15V$	--	5.8	--	
$t_{d(OFF)}$	Turn-Off Delay Time	$V_{GS}=-10V$	--	57	--	
t_f	Fall Time	$R_G=3.0\Omega$	--	116	--	
Q_g	Total Gate Charge	$V_{GS}=-10V$	--	60	--	nC
Q_{gs}	Gate to Source Charge	$V_{DS}=-15V$	--	8.2	--	
Q_{gd}	Gate to Drain Charge	$I_D=-5.0A$	--	11	--	

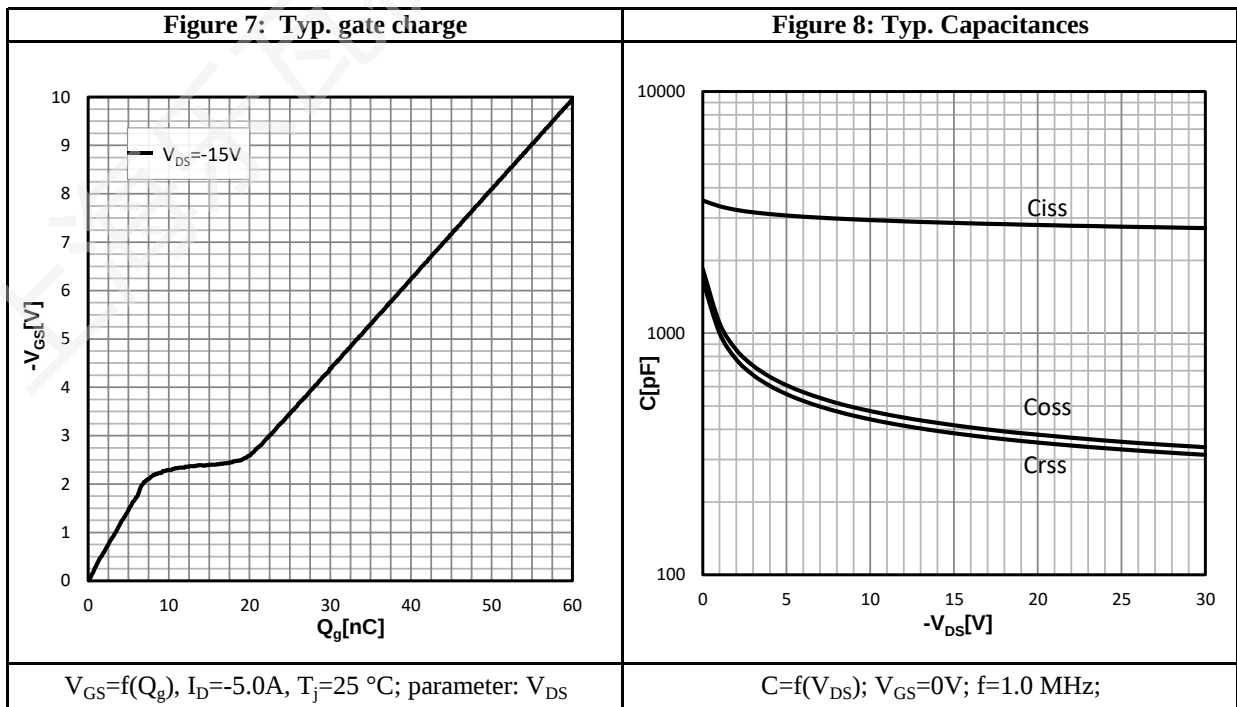
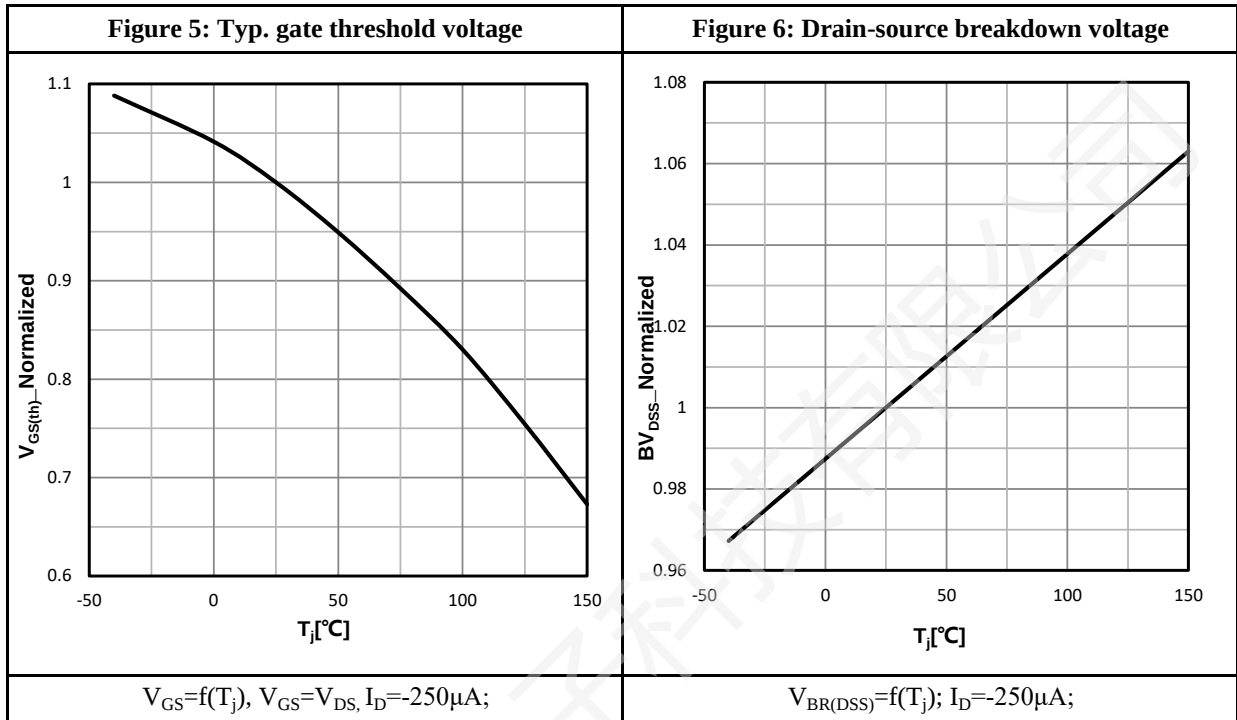
Source-Drain Diode Characteristics						
Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
I_S	Diode Forward Current	$T_A=25\text{ }^{\circ}\text{C}$	--	--	-16	A
V_{SD}	Diode Forward Voltage	$I_S=-15A, V_{GS}=0V$	--	--	-1.2	V

a1: Repetitive rating; pulse width limited by maximum junction temperature

a2: $V_{DD}=-15V, L=0.5mH, R_G=25\Omega$, Starting $T_J=25\text{ }^{\circ}\text{C}$

a3: Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm² (one layer, 70 μm thick) copper area for drain connection.

Characteristics Curve:




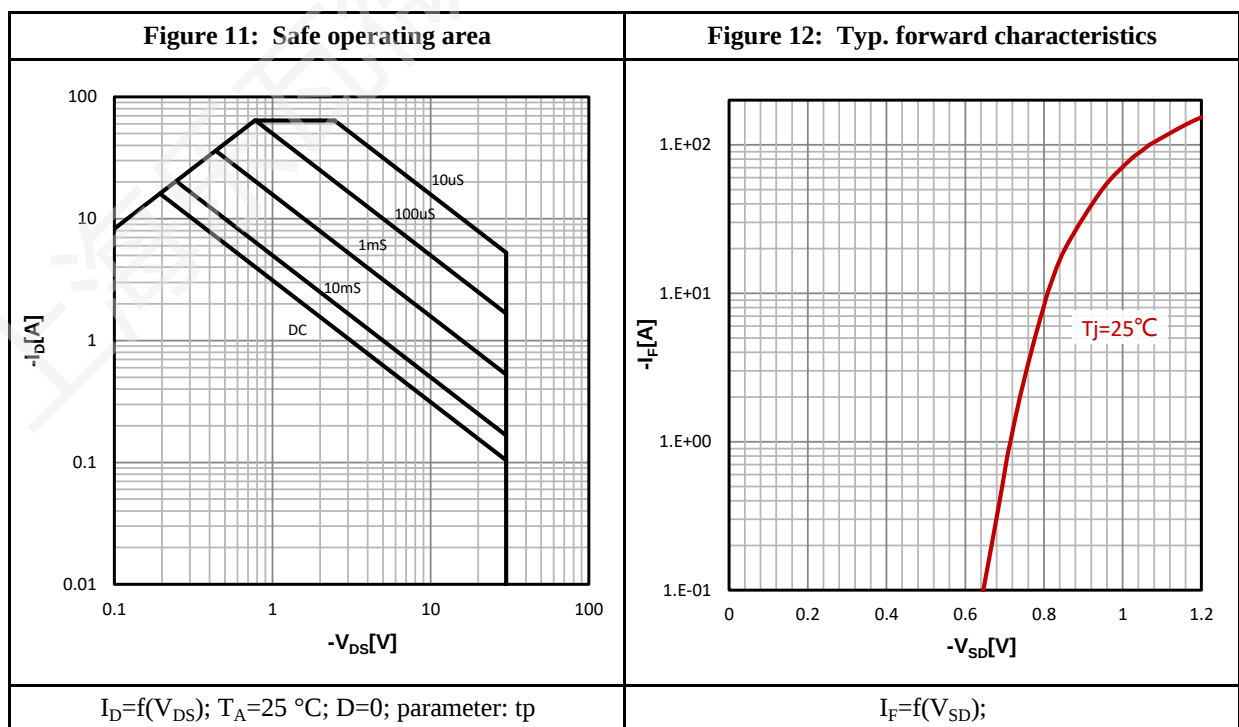
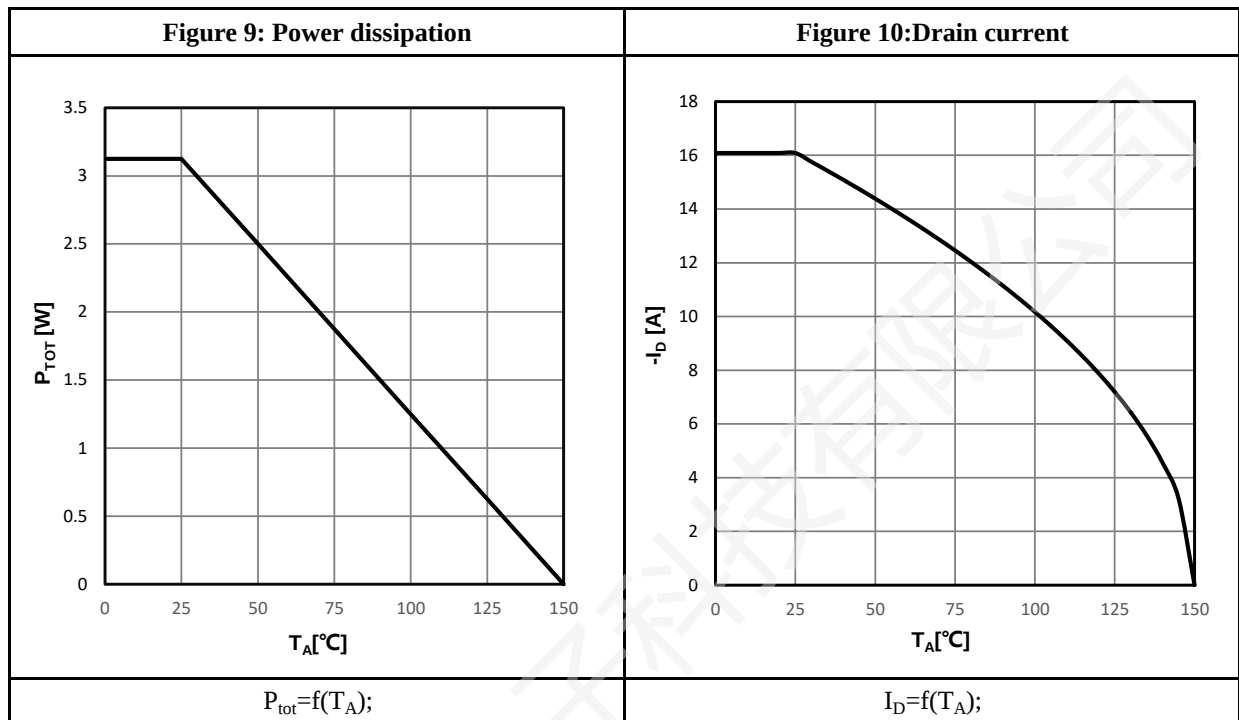
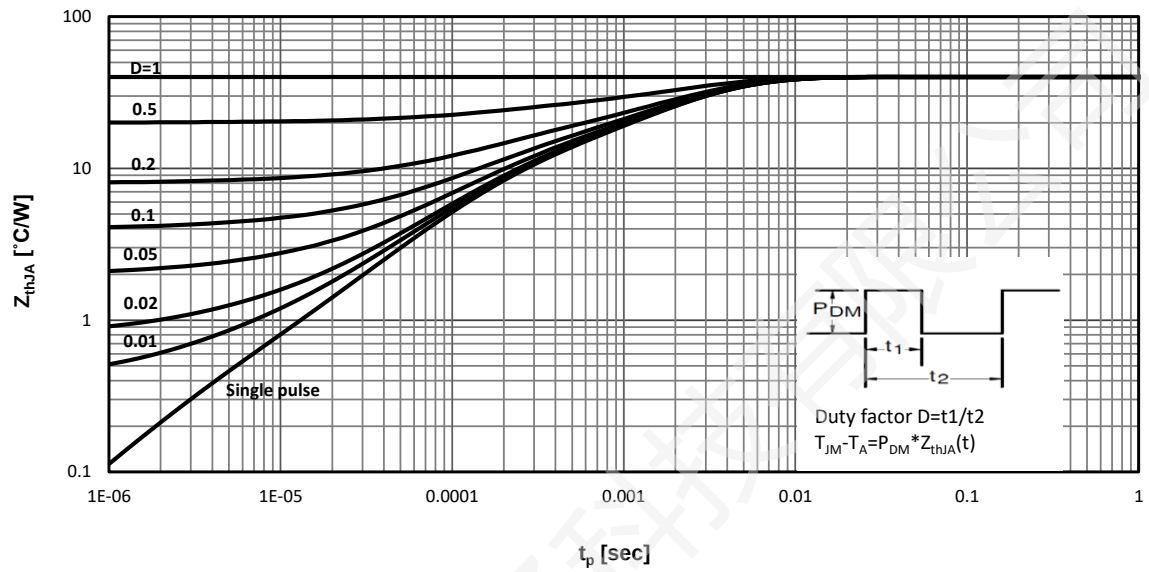
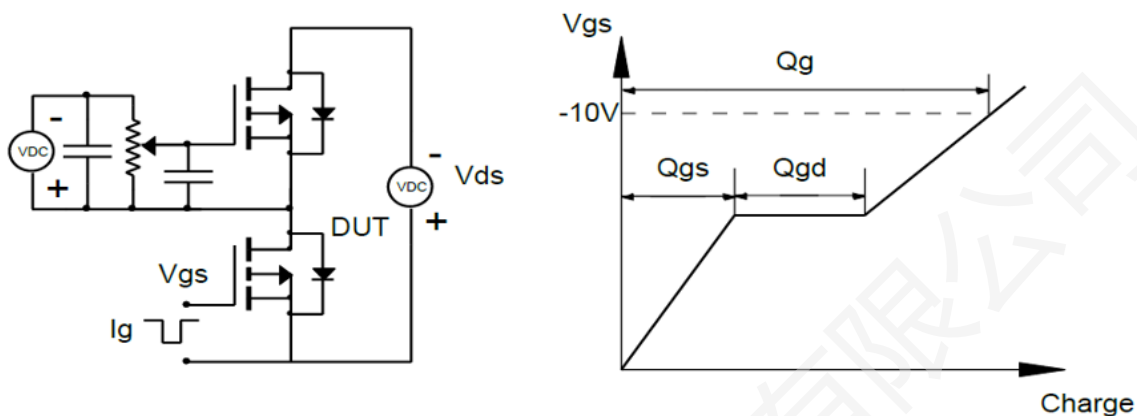
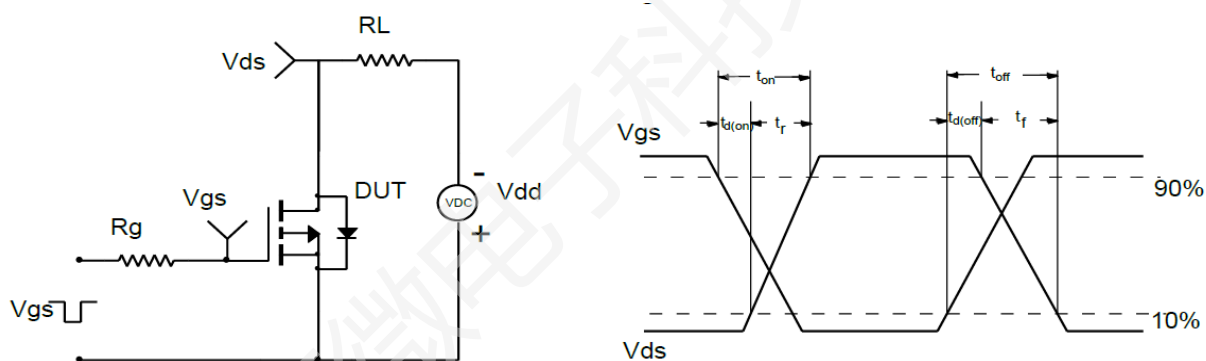
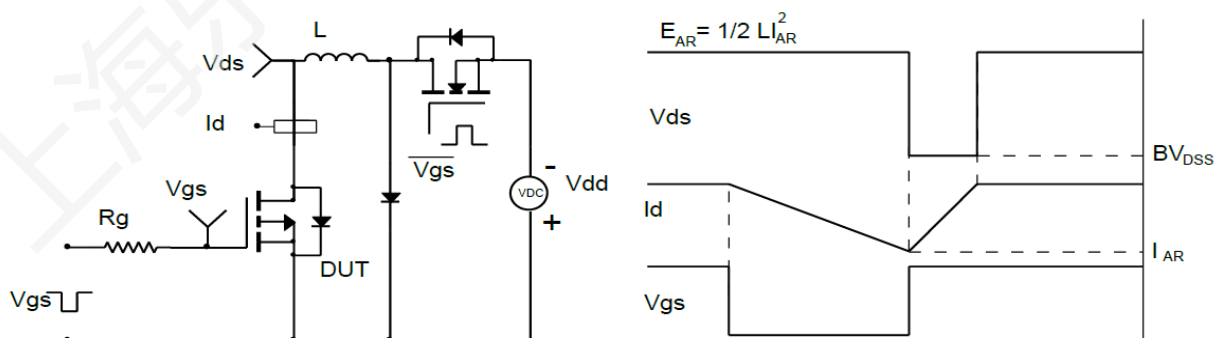
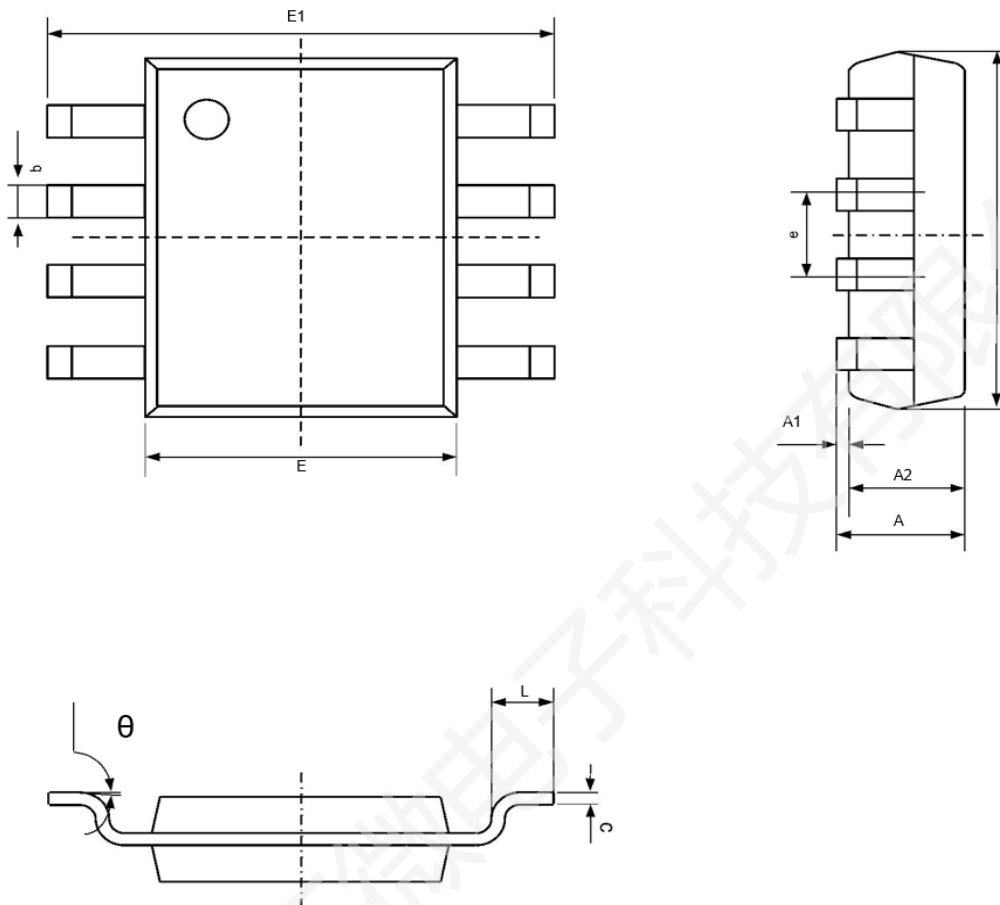


Figure 13: Max. Transient Thermal Impedance


$$Z_{thJA} = f(t_p); \text{ parameter: } D$$

Test Circuit & Waveform:

Figure 14: Gate Charge Test Circuit & Waveform

Figure 15: Resistive Switching Test Circuit & Waveforms

Figure 16: Unclamped Inductive Switching Test Circuit & Waveforms

Package Outline:


Symbol	Dimensions In Millimeters		
	Min	Ref	Max
A	1.350	1.550	1.750
A1	0.030	0.140	0.250
A2	1.350	1.450	1.550
b	0.330	0.430	0.530
c	0.160	0.205	0.250
D	4.700	5.000	5.300
E	3.800	3.900	4.000
E1	5.800	6.000	6.200
e	1.270(BSC)		
L	0.400	0.835	1.270
θ	0°	4°	8°

Revision History:

Revison	Date	Descriptions
Rev 1.0	July.2025	Initial Version

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